

Press Release

Embedded World 2022

KIOXIA Booth: 3A-117

KIOXIA First to Introduce JEDEC XFM Ver.1.0-Compliant PCIe/NVMe Removable Storage Device

New KIOXIA XFMEXPRESS XT2 Now Sampling



Düsseldorf, Germany, 14 June 2022 – <u>KIOXIA Europe GmbH</u> today announced sampling of the industry's first^[1] XFM Ver.1.0-compliant removable PCle attached, NVMe storage device in capacities of 256GB and 512GB: the XFMEXPRESS XT2. With the new XT2 form factor and connector, the XFM Ver.1.0 standard storage device delivers an unparalleled combination of



features designed to revolutionize ultra-mobile PCs, IoT devices and various embedded applications.

First introduced in August of 2019, and then presented as a proposal to the JEDEC Subcommittee for Electrical Specifications and Command Protocols, KIOXIA XFMEXPRESS XT2 is a new form factor for PCle/NVMe devices. Featuring a powerful combination of small size, speed and serviceability, XFMEXPRESS technology was developed to enhance next-generation mobile and embedded applications. KIOXIA XFMEXPRESS XT2 is the first product to meet the specification of the JEDEC standard.

KIOXIA XFMEXPRESS XT2 Key Features and Benefits:

Game-Changing Serviceability

The XFMEXPRESS XT2 enables a new category of small storage devices that are easy to service or upgrade. By pairing a robust, compact package with removable storage functionality and flexibility, the XFMEXPRESS XT2 helps diminish technical barriers and design constraints.

Mobile-Friendly Footprint

The JEDEC XFM DEVICE Ver.1.0 form factor's small size and low profile (14mm x 18mm x 1.4mm) offers a 252mm^[2] footprint, optimizing the mounting space for ultra-compact host devices without sacrificing performance or serviceability. With this minimized z-height, the XFMEXPRESS XT2's form factor is excellent for thin and light notebooks and creates new design possibilities for next generation applications and systems.

Interface

Designed for speed, the XFMEXPRESS XT2 implements a PCIe 4.0 x 2 lanes, NVMe 1.4b interface. The XFMEXPRESS XT2's industry-leading^[3] performance capabilities and durable form factor provide a compelling alternative to other SSD form factors (such as M.2), enabling superior computing and entertainment experiences.

"Recognizing the need for a new class of removable storage, KIOXIA, inventor of flash memory, leveraged its extensive background in single package memory designs to develop the XFMEXPRESS XT2." comments, Axel Stoermann, Vice President for Memory Marketing & Engineering, KIOXIA Europe GmbH. "We are planning to innovate and lead the way forward with more breakthrough storage solutions for complex design challenges in the future."



KIOXIA will demonstrate its XT2 solution live at <u>Embedded World 2022</u> in Nurnberg, Germany from 21-23 June in Hall 3A booth #3A-117 as well as the <u>Flash Memory Summit 2022</u> from 02-04 August at the Santa Clara Convention Center, California.

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Notes

[1] As of 14th June 2022, source: KIOXIA survey

[2] 22.2mm x 17.75mm x 2.2mm drive and connector

[3] As of June 2022, when compared to other PCIe NVMe form factors including M.2 and microSD

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About KIOXIA Europe GmbH

KIOXIA Europe GmbH (formerly Toshiba Memory Europe GmbH) is the European-based subsidiary of KIOXIA Corporation, a leading worldwide supplier of flash memory and solid-state drives (SSDs). From the invention of flash memory to today's breakthrough BiCS FLASH, KIOXIA continues to pioneer cutting-edge memory solutions and services that enrich people's lives and expand society's horizons. The company's innovative 3D flash memory technology, BiCS FLASH, is shaping the future of storage in high-density applications, including advanced smartphones, PCs, SSDs, automotive and data centers.

Visit our KIOXIA website

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